

SSC8036GN4

N-Channel Enhancement Mode MOSFET

> Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	l _D
30V	1.00)/	14mΩ@10V	224
	±20V	21mΩ@4V5	33A

Description

This device is N-Channel enhancement MOSFET.

Uses advanced trench technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + Δ VDS + Rg Tested!

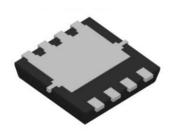
> Applications

- Motor Drive Control
- Power Supplies
- Synchronous Rectification
- DCDC Conversion

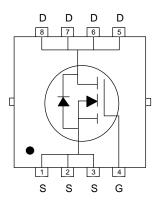
Ordering Information

Device	Package	Shipping	
SSC8036GN4	PDFN3.3X3.3-8L	5000/Reel	

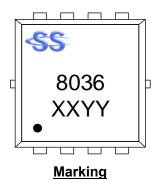
Pin Configuration



PDFN3.3X3.3-8L (Bottom View)



Pin Configuration



(XXYY: Internal Traceability Code)



Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

Parameter	Symbol	Ratings	Unit		
Drain-to-Source Voltage	V_{DSS}	30	V		
Gate-to-Source Voltage	V _{GSS}	±20	V		
Continuous Dunin Cumout d	T _C =25℃		33		
Continuous Drain Current d	T _C =100℃	l _D	18.5	Α	
Continuous Busin Comment 2	T _A =25℃		11.8	А	
Continuous Drain Current ^a	T _A =70°C	IDSM	8.7		
Pulsed Drain Current b	I _{DS}	133	Α		
Device Discipation C	Tc=25℃	Б	25	١٨/	
Power Dissipation °	T _C =100°C	P _D	10	W	
Device Discipation 2	T _A =25℃	Б	3.1	١٨/	
Power Dissipation ^a	T _A =70 °C	P _D	2	W	
Avalanche Current ^b L=0.5mH Sin	I _{AS}	9.6	Α		
Avalanche Energy ^b L=0.5mH Sin	Eas	28	mJ		
Operation junction temperat	TJ	-55~150	$^{\circ}$ C		
Storage temperature rang	T _{STG}	-55~150	C		

➤ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

Parameter	Typical	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance a	Reja	40	52	°C/W
Junction-to-Case Thermal Resistance	R _{θJC}	5	6.5	C/VV

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25°C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.



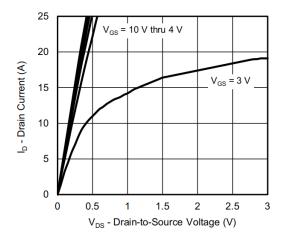


\succ Electrical Characteristics (T_A=25°C unless otherwise noted)

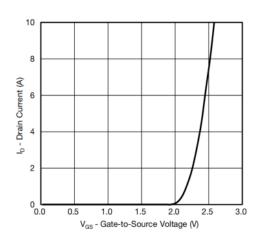
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	1.7	3	V
Drain-Source On-Resistance	Б	V _{GS} = 10V, I _D = 12A		14	18	0
Drain-Source On-Resistance	KDS(on)	$R_{DS(on)}$ $V_{GS} = 4.5V, I_D = 8A$		21	27	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	Igss	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Transconductance	G _{FS}	V _{DS} = 15V, I _D = 12A		32		s
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 1A		0.7	1	V
Gate Resistance	Rg	V _{DS} = 0V, f=1MHZ		2.3		Ω
Input Capacitance	Ciss	V - 45V V - 0V		715		
Output Capacitance	Coss	V _{DS} = 15V, V _{GS} = 0V,		81		pF
Reverse Transfer Capacitance	Crss	f = 1MHz		67		
Total Gate Charge	Q _G	10//// 45//		16.7		
Gate to Source Charge	Q _G s	$V_{GS} = 10V, V_{DS} = 15V,$		2.4		nC
Gate to Drain Charge	Q _{GD}	- I _D =15A		2.6		
Turn-on Delay Time	$T_{D(ON)}$			17		
Rise Time	Tr	V _{GS} = 10V, V _{DS} = 15V,		32		
Turn-off Delay Time	T _{D(OFF)}	$R_L = 10\Omega$, $R_G = 1\Omega$		16		ns
Fall Time	T _f			33		
Diode Recovery Time	Trr	I _F =10A, di/dt=100A/us		22		ns
Diode Recovery Charge	Q _{rr}	I _F =10A, di/dt=100A/us		15		nC



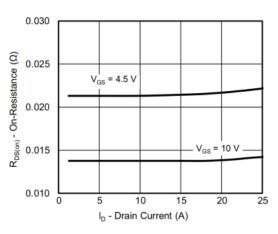
➤ Typical Performance Characteristics (T_A=25°C unless otherwise noted)



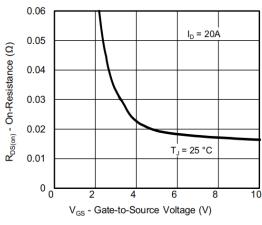
Output Characteristics



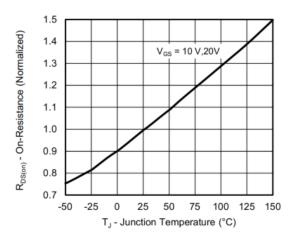
Transfer Characteristics



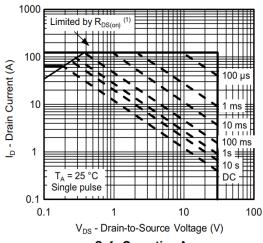
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage



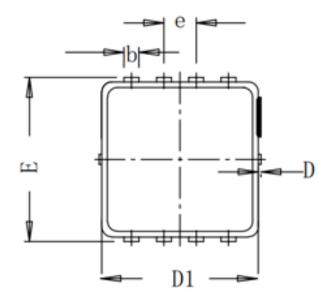
On-Resistance vs. Junction Temperature

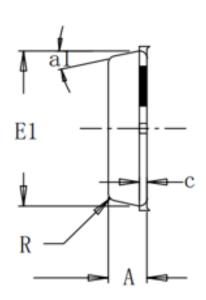


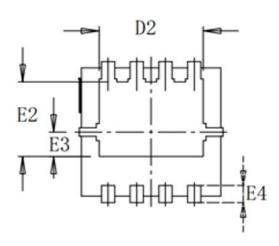
Safe Operating Area



> Package Information







Cumbal	Dimensions In Millimeters				
Symbol	Min.	Nom.	Max.		
Α	0.75	0.78	0.81		
b	0.297	0.3	0.35		
С	-	0.152	•		
D	0	0.05	0.1		
D1	3.12	3.15	3.18		
D2	-	2.35	-		
E	3.2	3.3	3.4		
E1	3.09	3.12	3.15		
E2	-	1.75	-		
E3	-	0.575	-		
E4	-	0.4	-		
R	-	0.15	-		
е	0.65BSC				
a1°	-	12° -			



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